What is claimed is:

Sub A1

1. A hybrid integrated circuit device comprising: a substrate in which at least a surface is provided with insulation; a first electrode and a second electrode formed on the surface; a light emitting element connected with the first and second electrode; a seal which is disposed in a periphery of said substrate; and a transparent substrate which is fixed via said seal.

2. A hybrid integrated circuit device according to claim 1, which comprises:

a substrate in which at least a surface is provided with insulation;

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a first electrode which is formed on a region of the surface of said substrate, and which is made of Cu covered with an oxidation resistant metal;

a second electrode which is formed on another region of said substrate, and which is made of Cu covered with an oxidation resistant metal;

a light emitting element in which a rear face of a chip is electrically fixed to said first electrode;

connecting means for electrically connecting said second electrode to an electrode which is on a surface of

said light emitting element;

a seal which is disposed in a periphery of said substrate; and

a transparent substrate which is fixed via said seal.

3. A hybrid integrated circuit device according to claim 1, wherein a plurality of hybrid integrated circuit substrates are arranged, each of said hybrid integrated circuit substrates comprising:

a substrate in which at least a surface is provided with insulation;

a first electrode which is formed on a region of the surface of said substrate, and which is made of Cu covered with an oxidation resistant metal;

a second electrode which is formed on another region of said substrate, and which is made of Cu covered with an oxidation resistant metal;

a light emitting element in which a rear face of a chip is electrically fixed to said first electrode;

connecting means for electrically connecting said second electrode to an electrode which is on a surface of said light emitting element;

a seal which is disposed in a periphery of said substrate; and

a transparent substrate which is fixed via said seal, and connecting means for electrically connecting said first and second electrodes on said hybrid integrated circuit substrates with one other in order to enable said light emitting element on said hybrid integrated circuit substrates to emit light is disposed.

Sub A2

4. A hybrid integrated circuit device according to claim 1, wherein a gas for preventing said light emitting element and/or said electrodes from deteriorating is filled into a space defined by said substrate, said transparent substrate, and said seal.

5. A hybrid integrated circuit device according to claim 1, wherein a spacer which is made of an insulating material is disposed inside said seal.

6. A hybrid integrated circuit device according to claim 1, wherein a light transmitting resin which is formed into a lens-like shape is disposed in said light emitting element.

7. A hybrid integrated circuit device according to claim 6, wherein a top portion of said light transmitting resin abuts against said transparent substrate.

Sub A3

8. A hybrid integrated circuit device according to claim 3, wherein said hybrid integrated circuit substrates are arranged in a matrix form, and at least end ones of said hybrid integrated circuit substrates are inclined at a predetermined angle with respect to a center one of said hybrid integrated circuit substrates.

9. A hybrid integrated circuit device according to claim 1, wherein said seal is made of a glossy material which reflects light emitted from said light emitting element.

10. A hybrid integrated circuit device according to claim 1, wherein a filling hole for the gas is formed in said seal.

11. A hybrid integrated circuit device according to claim 9, wherein said seal is made of a brazing material formed on a metal film which can be wet with the brazing material.

12. A hybrid integrated circuit device according to claim 1, further comprising an exhausting hole for a gas included inside said seal and a filling hole for the gas which are formed in said seal, wherein the exhausting hole

and the filling hole are sealed after exhausting and filling a gas.

13. A hybrid integrated circuit device according to claim 1, wherein said gas is an inert gas.

Sub A14

14. A hybrid integrated circuit device according to claim 1, wherein the surface of the substrate is covered with solder resist.

15. A hybrid integrated circuit device according to claim 1, wherein the substrate is made of glass.

16. A hybrid integrated circuit device according to claim 8, wherein the substrates are arranged in a matrix form and at least both end substrates is inclined in vertical and lateral directions so as to realize a paraboloid, and an object to be heated is disposed in a focus of the paraboloid surface.

Add A5